RENESAS

PLL AUDIO CLOCK SYNTHESIZER

MK2703

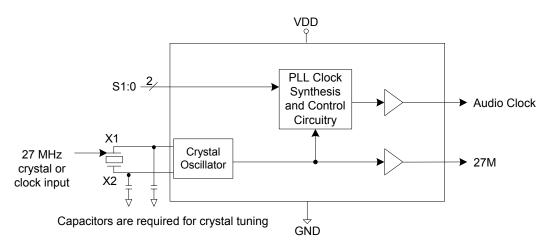
Description

The MK2703 is a low-cost, low-jitter, high-performance PLL clock synthesizer designed to replace oscillators and PLL circuits in set-top box and multimedia systems. Using IDT's patented analog Phase Locked Loop (PLL) techniques, the device uses a 27 MHz crystal or clock input to produce a buffered reference clock and a selectable audio clock.

IDT manufactures the largest variety of Set-Top Box and multimedia clock synthesizers for all applications. Consult IDT to eliminate VCXOs, crystals and oscillators from your board.

Features

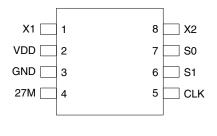
- Packaged in 8-pin SOIC
- Pb (lead) free package
- Uses an inexpensive, fundamental mode crystal or clock
- Supports MPEG sampling rates of 32 kHz, 44.1 kHz, 48 kHz, and 96 kHz
- · Patented zero ppm synthesis error in all clocks
- All frequencies are frequency locked
- Advanced, low power, sub-micron CMOS process
- Operating voltage of 3.3 V or 5 V
- Industrial temperature version available
- The MK2703B is recommended for new designs



Block Diagram

Pin Assignment

Pin Descriptions



8-pin (150 mil) SOIC

AUDIO CLOCK OUTPUT SELECT TABLE

S1	S0	CLK (MHz)
0	0 8.192	
0	1	11.2896
1	0	12.288
1	1	24.576

Key: 0 = Connect pin directly to ground

1 = Connect pin directly to VDD

Pin Pin Pin **Pin Description** Number Name Type 1 X1 XI Crystal Connection. Connect to a 27 MHz fundamental crystal or clock. VDD 2 Power Connect to +3.3 V or +5 V. 3 GND Power Connect to ground. 4 27M Output 27 MHz buffered reference clock output. 5 CLK Output Audio clock output per table above. S1 Audio clock frequency select input #1. Determines CLK output per table 6 Input above. Internal pull-up resistor. 7 S0 Audio clock frequency select input #0. Determines CLK output per table Input above. Internal pull-up resistor. 8 X2 XO Crystal connection to a 27 MHz crystal, or leave unconnected for clock output.

External Components

Decoupling Capacitor

As with any high-performance mixed-signal IC, the MK2703 must be isolated from system power supply noise to perform optimally.

A decoupling capacitor of 0.01µF must be connected between VDD and GND on pins 2 and 3. It must be connected close to the MK2703 to minimize lead inductance. No external power supply filtering is required for the MK2703.

Series Termination Resistor

A 33Ω terminating resistor can be used next to the clock outputs for trace lengths over one inch.

Crystal Load Capacitors

The total on-chip capacitance is approximately 16 pF. A parallel resonant, fundamental mode, AT cut 27 MHz crystal should be used. The device crystal connections should include pads for small capacitors from X1 to ground and from X2 to ground. These capacitors are used to adjust the

stray capacitance of the board to match the nominally required crystal load capacitance. Because load capacitance can only be increased in this trimming process, it is important to keep stray capacitance to a minimum by using very short PCB traces (and no vias) between the crystal and device. Crystal capacitors, if needed, must be connected from each of the pins X1 and X2 to ground.

The value (in pF) of these crystal caps should equal (C_L -16 pF)*2. In this equation, C_L= crystal load capacitance in pF. Example: For a crystal with an 18 pF load capacitance, each crystal capacitor would be 4 pF [(18-16) x 2] = 4.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the MK2703. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	-0.5 V to 7 V
All Inputs and Outputs	-0.5 V to VDD+0.5 V
Ambient Operating Temperature, MK2703S (commercial)	0 to +70° C
Ambient Operating Temperature, MK2703SI (industrial)	-40 to +85° C
Storage Temperature	-65 to +150° C
Soldering Temperature	260° C

Recommended Operation Conditions

Parameter	Min.	Тур.	Max.	Units
Ambient Operating Temperature	-40		+85	°C
Power Supply Voltage (measured in respect to GND)	+3.13		+5.50	V

DC Electrical Characteristics

VDD=3.3 V ±5% , Ambient temperature -40 to +85° C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		3.13		5.50	V
Input High Voltage	V _{IH}	X1 pin only Note 1	(VDD/2)+1	VDD/2		V
Input Low Voltage	V _{IL}	X1 pin only Note 1		VDD/2	(VDD/2)-1	V
Input High Voltage	V _{IH}	S0, S1 pins	2.0			V
Input Low Voltage	V _{IL}	S0, S1 pins			0.8	V
Output High Voltage	V _{OH}	I _{OH} = -12 mA	2.4			V

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Output Low Voltage	V _{OL}	I _{OL} = 12 mA			0.4	V
Output High Voltage, CMOS level	V _{OH}	I _{OH} = -4 mA	VDD-0.4			V
Operating Supply Current	IDD	No load VDD = 3.3 V		25		mA
Short Circuit Current		CLK output		<u>+</u> 50		mA
Input Capacitance	C _{IN}	S0, S1 pins		5		pF
Nominal Output Impedance				20		Ω
Frequency Synthesis Error		All Clocks			0	ppm
Internal Pull-up Resistor	R _{PUP}	S1, S0 pins		500		kΩ

Note 1: CMOS level input. Nominal trigger point is VDD/2 for 3.3 V or 5 V operation.

AC Electrical Characteristics

VDD = 3.3 V ±5%, Ambient Temperature -40 to	+85° C, unless stated otherwise
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Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Crystal or Clock Frequency	F _{IN}			27		MHz
Output Clock Rise Time	t _{OR}	0.8 to 2.0 V, Note 1			1.5	ns
Output Clock Fall Time	t _{OF}	2.0 to 8.0 V, Note 1			1.5	ns
Clock Stabilization Time after Power-up					10	ms
Changing Frequency Setting					10	ms
Output Clock Duty Cycle		at VDD/2, Note 1	40		60	%
Maximum Absolute Jitter, short term	t _{ja}	Deviation from mean		±190		ps

Note 1: Measured with 15 pF load.

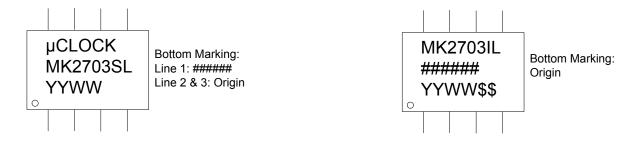
Thermal Characteristics

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Thermal Resistance Junction to	θ_{JA}	Still air		150		° C/W
Ambient	θ_{JA}	1 m/s air flow		140		° C/W
	θ_{JA}	3 m/s air flow		120		° C/W
Thermal Resistance Junction to Case	θ_{JC}			40		° C/W

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Marking Diagram - MK2703SLF

Marking Diagram - MK2703SILF

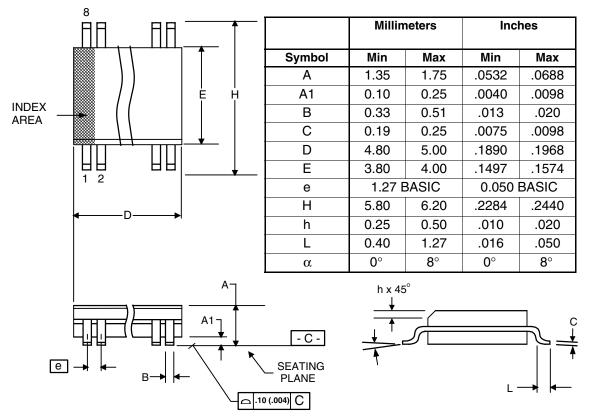


Notes:

- 1. ###### is the lot number.
- 2. YYWW is the last two digits of the year and the week number that the part was assembled.
- 3. Bottom mark denotes country of origin.

Package Outline and Package Dimensions (8-pin SOIC, 150 Mil. Narrow Body)

Package dimensions are kept current with JEDEC Publication No. 95



Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
MK2703SLF	500 paga 5	Tubes	8-pin SOIC	0 to +70° C
MK2703SLFTR	see page 5	Tape and Reel	8-pin SOIC	0 to +70° C
MK2703SILF	000 0000 F	Tubes	8-pin SOIC	-40 to +85° C
MK2703SILFTR	see page 5	Tape and Reel	8-pin SOIC	-40 to +85° C

"LF" denotes Pb (lead) free package.

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